2814 AF

PATENT Atty. Dkt. No. AMAT/1931/CALB/COPPER/PJS

Atty. Dkt. No. AMAT/1931/CAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chen et al.

Serial No.: 08/856,116

Confirmation No.:

2582

Filed:

JAN 1 8 2002

May 14, 1997

For:

RELIABILITY BARRIER

INTEGRATION FOR CU

**APPLICATION** 

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

Group Art Unit: 2814

Examiner:

G. Peralta

CERTIFICATE OF MAILING 37 CFR 1.8

I hereby certify that this correspondence is being deposited on <u>December 2.0, 2001</u>, with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

12/20/01

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Signature

## **RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 10, 2001**

In response to the Final Office Action dated October 10, 2001, having a shortened statutory period for response set to expire on January 10, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below.

## THE PENDING CLAIMS:

- 15. A method of filling a feature in a dielectric layer, comprising:
  - a) depositing a first barrier layer over a blanket dielectric layer;
- b) forming a feature through the first barrier layer and the dielectric layer to expose an underlayer;
- c) depositing a second barrier layer on a bottom and sidewalls in the feature;
- d) removing the second barrier layer formed at the bottom of the feature; and